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Product Change Notification - KMIO-10XRFH058

Date: 18 Oct 2016
Product Category: Analog (Thermal, Power Management & Safety)
Notification subject: CCB 2761 Initial Notice: Qualification of CuPdAu wire, 8600 die attach and G700LTD mold compound in selected products of the 200K wafer technology available in 8L TDFN package at NSEB assembly site
Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material in selected products of the 200K wafer technology available in 8L TDFN package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire, 8200T die attach and G770HCD mold compound material.

Post Change:

Using palladium coated copper with gold flash CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB assembly site	NSEB assembly site
Wire material	Au wire	CuPdAu wire
Die attach material	8200T	8600
Molding compound material	G770HCD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability and qualify palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

February 17, 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date.

Time Table Summary:

	October 2016				->	February 2017				
Workweek	41	42	43	44		5	6	7	8	9
Initial PCN Issue Date		X								
Qual Report Availability								X		
Final PCN Issue Date								X		

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:

October 14, 2016: Issued initial notification.

October 18, 2016: Re-issued initial notification to correct the attachments.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KMIO-10XRFH058_Qual Plan.pdf](#)

[PCN_KMIO-10XRFH058_Affected_CPN.pdf](#)

[PCN_KMIO-10XRFH058_Affected_CPN.xls](#)

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KMIO-06TADJ110- Qualification of G700HA mold compound for selected products available on 80L TQFP (12x12 mm) at MTAI assembly site.

Affected Catalog Part Number (CPN)

PCN_KMIO-10XRFH058
CATALOG_PART_NBR
MCP98244T-BE/MNY
MCP98244T-BE/MNYAA
MCP98244T-BE/MNYAB
MCP98244T-BE/MNYAC
MCP9844T-BE/MNY
MCP9844T-BE/MNYAA
MCP9844T-BE/MNYAB